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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	3424
Number of Logic Elements/Cells	30816
Total RAM Bits	2506752
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp30-5fgg676c

Configurable Logic Blocks (CLBs)

The Virtex-II Pro configurable logic blocks (CLB) are organized in an array and are used to build combinatorial and synchronous logic designs. Each CLB element is tied to a switch matrix to access the general routing matrix, as shown in [Figure 32](#). A CLB element comprises 4 similar slices, with fast local feedback within the CLB. The four slices are split in two columns of two slices with two independent carry logic chains and one common shift chain.

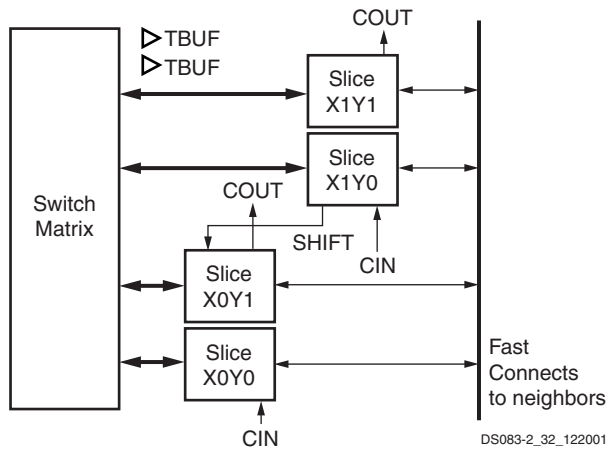


Figure 32: Virtex-II Pro CLB Element

Slice Description

Each slice includes two 4-input function generators, carry logic, arithmetic logic gates, wide function multiplexers and two storage elements. As shown in [Figure 33](#), each 4-input function generator is programmable as a 4-input LUT, 16 bits of distributed SelectRAM+ memory, or a 16-bit variable-tap shift register element.

The output from the function generator in each slice drives both the slice output and the D input of the storage element. [Figure 34](#) shows a more detailed view of a single slice.

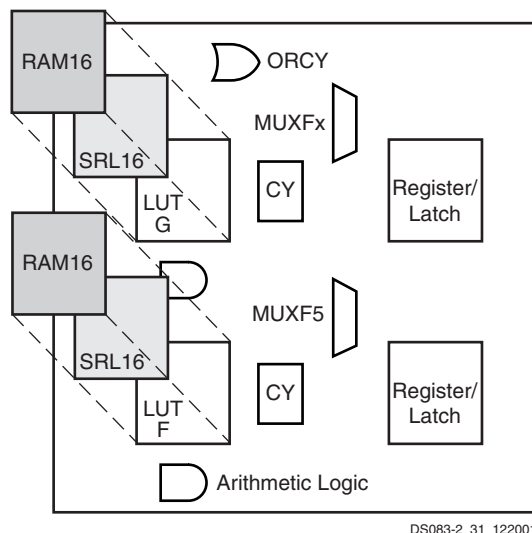


Figure 33: Virtex-II Pro Slice Configuration

Configurations

Look-Up Table

Virtex-II Pro function generators are implemented as 4-input look-up tables (LUTs). Four independent inputs are provided to each of the two function generators in a slice (F and G). These function generators are each capable of implementing any arbitrarily defined boolean function of four inputs. The propagation delay is therefore independent of the function implemented. Signals from the function generators can exit the slice (X or Y output), can input the XOR dedicated gate (see arithmetic logic), or input the carry-logic multiplexer (see fast look-ahead carry logic), or feed the D input of the storage element, or go to the MUXF5 (not shown in [Figure 34](#)).

In addition to the basic LUTs, the Virtex-II Pro slice contains logic (MUXF5 and MUXFx multiplexers) that combines function generators to provide any function of five, six, seven, or eight inputs. The MUXFx is either MUXF6, MUXF7, or MUXF8 according to the slice considered in the CLB. Selected functions up to nine inputs (MUXF5 multiplexer) can be implemented in one slice. The MUXFx can also be a MUXF6, MUXF7, or MUXF8 multiplexer to map any function of six, seven, or eight inputs and selected wide logic functions.

Register/Latch

The storage elements in a Virtex-II Pro slice can be configured either as edge-triggered D-type flip-flops or as level-sensitive latches. The D input can be directly driven by the X or Y output via the DX or DY input, or by the slice inputs bypassing the function generators via the BX or BY input. The clock enable signal (CE) is active High by default. If left unconnected, the clock enable for that storage element defaults to the active state.

In addition to clock (CK) and clock enable (CE) signals, each slice has set and reset signals (SR and BY slice inputs). SR forces the storage element into the state specified by the attribute SRHIGH or SRLOW. SRHIGH forces a logic 1 when SR is asserted. SRLOW forces a logic 0. When SR is used, an optional second input (BY) forces the storage element into the opposite state via the REV pin. The reset condition is predominant over the set condition. (See [Figure 35](#).)

The initial state after configuration or global initial state is defined by a separate INIT0 and INIT1 attribute. By default, setting the SRLOW attribute sets INIT0, and setting the SRHIGH attribute sets INIT1. For each slice, set and reset can be set to be synchronous or asynchronous. Virtex-II Pro devices also have the ability to set INIT0 and INIT1 independent of SRHIGH and SRLOW.

The control signals clock (CLK), clock enable (CE) and set/reset (SR) are common to both storage elements in one slice. All of the control signals have independent polarity. Any inverter placed on a control input is automatically absorbed.

Sum of Products

Each Virtex-II Pro slice has a dedicated OR gate named ORCY, ORing together outputs from the slices carryout and the ORCY from an adjacent slice. The ORCY gate with the dedicated Sum of Products (SOP) chain are designed for

implementing large, flexible SOP chains. One input of each ORCY is connected through the fast SOP chain to the output of the previous ORCY in the same slice row. The second input is connected to the output of the top MUXCY in the same slice, as shown in Figure 43.

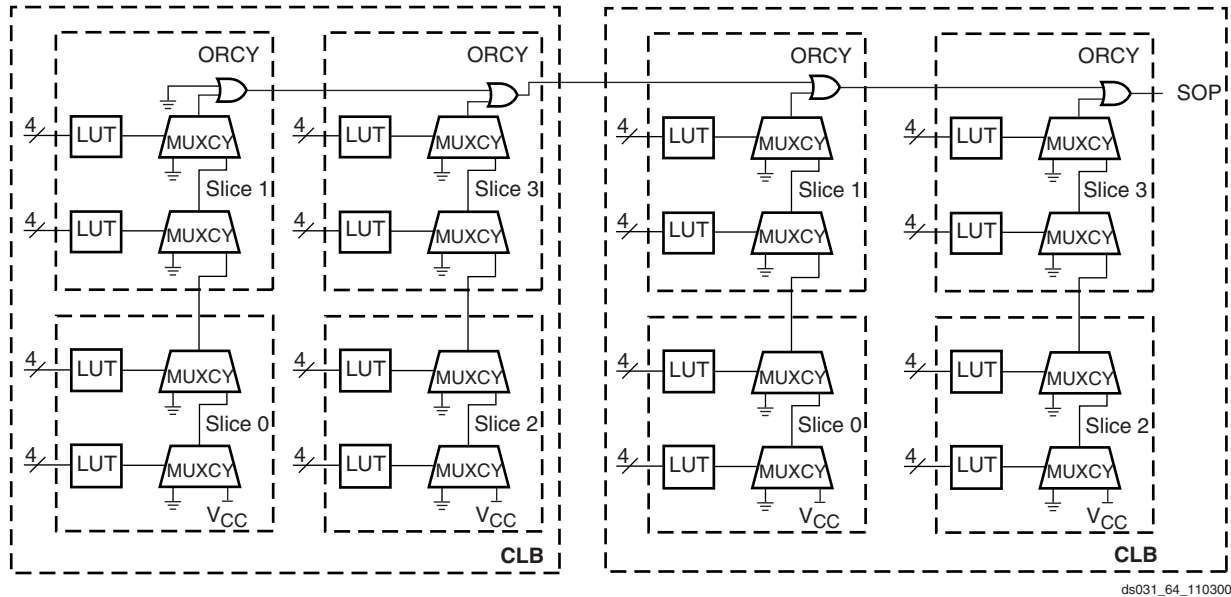


Figure 43: Horizontal Cascade Chain

LUTs and MUXCYs can implement large AND gates or other combinatorial logic functions. Figure 44 illustrates

LUT and MUXCY resources configured as a 16-input AND gate.

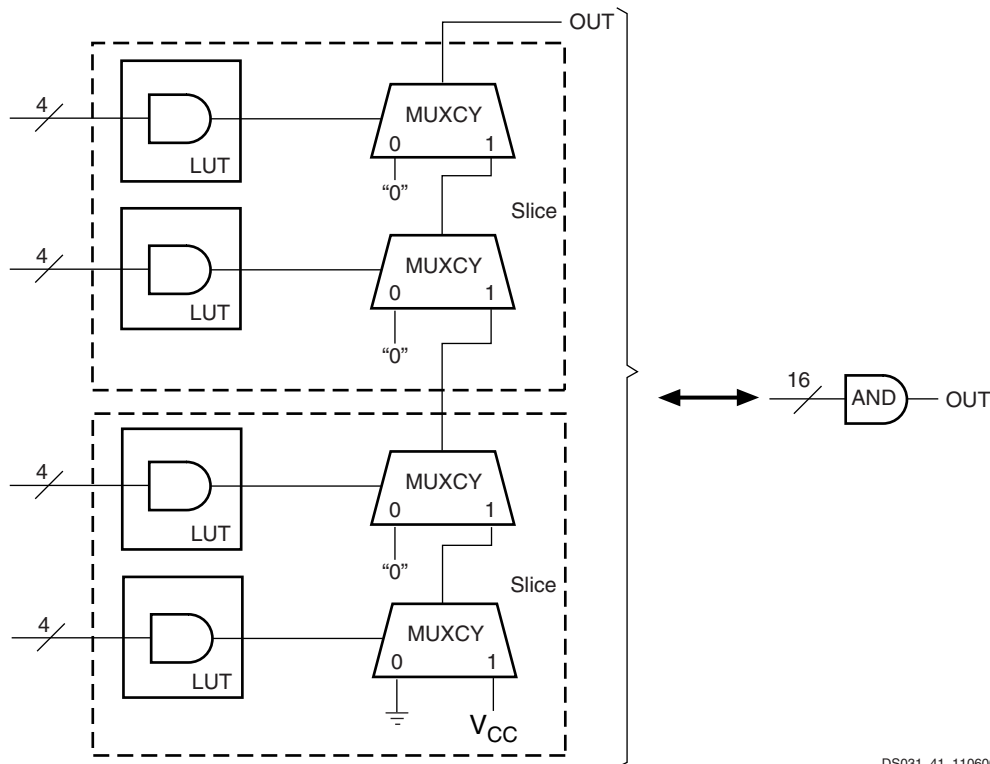


Figure 44: Wide-Input AND Gate (16 Inputs)



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

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Product Specification

Virtex-II Pro⁽¹⁾ Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade

commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

Virtex-II Pro DC Characteristics

Table 1: Absolute Maximum Ratings

Symbol	Description ⁽¹⁾	Virtex-II Pro X	Virtex-II Pro	Units
V _{CCINT}	Internal supply voltage relative to GND	–0.5 to 1.6		V
V _{CCAUX}	Auxiliary supply voltage relative to GND	–0.5 to 3.0		V
V _{CCO}	Output drivers supply voltage relative to GND	–0.5 to 3.75		V
V _{BATT}	Key memory battery backup supply	–0.5 to 4.05		V
V _{REF}	Input reference voltage	–0.3 to 3.75		V
V _{IN}	3.3V I/O input voltage relative to GND (user and dedicated I/Os)	–0.3 to 4.05 ⁽³⁾		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)	–0.5 to V _{CCO} + 0.5		V
V _{TS}	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)	–0.3 to 4.05 ⁽³⁾		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)	–0.5 to V _{CCO} + 0.5		V
AVCCAUXRX	Receive auxiliary supply voltage relative to GNDA (analog ground)	–0.5 to 2.0	–0.5 to 3.0	V
AVCCAUTX	Transmit auxiliary supply voltage relative to GNDA (analog ground)	–0.5 to 3.0	–0.5 to 3.0	V
V _{TRX}	Terminal receive supply voltage relative to GND	–0.5 to 3.0	–0.5 to 3.0	V
V _{TTX}	Terminal transmit supply voltage relative to GND	–0.5 to 1.6	–0.5 to 3.0	V
T _{STG}	Storage temperature (ambient)	–65 to +150		°C
T _{SOL}	Maximum soldering temperature ⁽²⁾	All regular FG/FF flip-chip packages		+220
		Pb-free FGG256 wire-bond package		N/A
		Pb-free FGG456 and FGG676 wire-bond packages		N/A
T _J	Maximum junction temperature ⁽²⁾	+125		°C

Notes:

- Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
- For soldering guidelines and thermal considerations, see the [Device Packaging and Thermal Characteristics Guide](#) information on the Xilinx website.
- 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to [XAPP659](#) for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Table 17: Processor Block Switching Characteristics

		Speed Grade			
Description	Symbol	-7	-6	-5	Units
Setup and Hold Relative to Clock (CPMC405CLOCK)					
Device Control Register Bus control inputs	T _{PCKC} _DCR/T _{PCKC} _DCR	0.38/−0.18	0.44/−0.20	0.48/−0.23	ns, min
Device Control Register Bus data inputs	T _{PDCK} _DCR/T _{PCKD} _DCR	0.65/−0.01	0.75/−0.01	0.82/−0.02	ns, min
Clock and Power Management control inputs	T _{PCKC} _CPM/T _{PCKC} _CPM	0.16/ 0.03	0.19/ 0.03	0.20/ 0.03	ns, min
Reset control inputs	T _{PCKC} _RST/T _{PCKC} _RST	0.16/ 0.03	0.19/ 0.03	0.20/ 0.03	ns, min
Debug control inputs	T _{PCKC} _DBG/T _{PCKC} _DBG	0.27/ 0.30	0.31/ 0.35	0.34/ 0.38	ns, min
Trace control inputs	T _{PCKC} _TRC/T _{PCKC} _TRC	1.37/−0.41	1.57/−0.48	1.73/−0.52	ns, min
External Interrupt Controller control inputs	T _{PCKC} _EIC/T _{PCKC} _EIC	0.57/−0.22	0.66/−0.25	0.72/−0.27	ns, min
Clock to Out					
Device Control Register Bus control outputs	T _{PCKCO} _DCR	1.32	1.52	1.67	ns, max
Device Control Register Bus address outputs	T _{PCKAO} _DCR	1.72	1.98	2.17	ns, max
Device Control Register Bus data outputs	T _{PCKDO} _DCR	1.76	2.02	2.22	ns, max
Clock and Power Management control outputs	T _{PCKCO} _CPM	1.26	1.45	1.59	ns, max
Reset control outputs	T _{PCKCO} _RST	1.32	1.51	1.66	ns, max
Debug control outputs	T _{PCKCO} _DBG	1.94	2.22	2.44	ns, max
Trace control outputs	T _{PCKCO} _TRC	1.35	1.56	1.71	ns, max
Clock					
CPMC405CLOCK minimum pulse width, high	T _{CPWH}	1.25	1.42	1.66	ns, min
CPMC405CLOCK minimum pulse width, low	T _{CPWL}	1.25	1.42	1.66	ns, min

Table 18: Processor Block PLB Switching Characteristics

		Speed Grade			
Description	Symbol	-7	-6	-5	Units
Setup and Hold Relative to Clock (PLBCLK)					
Processor Local Bus(ICU/DCU) control inputs	T _{PCKK} _PLB/T _{PCKC} _PLB	0.98/ 0.18	1.12/ 0.21	1.23/ 0.23	ns, min
Processor Local Bus (ICU/DCU) data inputs	T _{PDCK} _PLB/T _{PCKD} _PLB	0.62/ 0.16	0.71/ 0.18	0.78/ 0.20	ns, min
Clock to Out					
Processor Local Bus(ICU/DCU) control outputs	T _{PCKCO} _PLB	1.34	1.54	1.69	ns, max
Processor Local Bus(ICU/DCU) address bus outputs	T _{PCKAO} _PLB	1.16	1.34	1.47	ns, max
Processor Local Bus(ICU/DCU) data bus outputs	T _{PCKDO} _PLB	1.44	1.65	1.81	ns, max

Output Clock Jitter

Table 59: Output Clock Jitter

Description	Symbol	Constraints	Speed Grade			Units
			–7	–6	–5	
Clock Synthesis Period Jitter						
CLK0	CLKOUT_PER_JITT_0		±100	±100	±100	ps
CLK90	CLKOUT_PER_JITT_90		±150	±150	±150	ps
CLK180	CLKOUT_PER_JITT_180		±150	±150	±150	ps
CLK270	CLKOUT_PER_JITT_270		±150	±150	±150	ps
CLK2X, CLK2X180	CLKOUT_PER_JITT_2X		±200	±200	±200	ps
CLKDV (integer division)	CLKOUT_PER_JITT_DV1		±150	±150	±150	ps
CLKDV (non-integer division)	CLKOUT_PER_JITT_DV2		±300	±300	±300	ps
CLKFX, CLKFX180	CLKOUT_PER_JITT_FX		Note (1)	Note (1)	Note (1)	ps

Notes:

1. Use the **Jitter Calculator** on the Xilinx website (http://www.xilinx.com/applications/web_ds_v2/jitter_calc.htm) for CLKFX and CLKFX180 output jitter.

Output Clock Phase Alignment

Table 60: Output Clock Phase Alignment

Description	Symbol	Constraints	Speed Grade			Units
			–7	–6	–5	
Phase Offset Between CLKIN and CLKFB						
CLKIN/CLKFB	CLKIN_CLKFB_PHASE		±50	±50	±50	ps
Phase Offset Between Any DCM Outputs						
All CLK* outputs	CLKOUT_PHASE		±140	±140	±140	ps
Duty Cycle Precision						
DLL outputs ⁽¹⁾	CLKOUT_DUTY_CYCLE_DLL ⁽²⁾		±150	±150	±150	ps
CLKFX outputs	CLKOUT_DUTY_CYCLE_FX		±100	±100	±100	ps

Notes:

1. “DLL outputs” is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. CLKOUT_DUTY_CYCLE_DLL applies to the 1X clock outputs (CLK0, CLK90, CLK180, and CLK270) only if DUTY_CYCLE_CORRECTION = TRUE.
3. Specification also applies to PSCLK.

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
5	IO_L46N_5	W11			
5	IO_L46P_5	W10			
5	IO_L45N_5/VREF_5	AD9			
5	IO_L45P_5	AC9			
5	IO_L43N_5	AB9			
5	IO_L43P_5	AA9			
5	IO_L39N_5	Y9			
5	IO_L39P_5	W9			
5	IO_L37N_5	AF8			
5	IO_L37P_5	AE8			
5	IO_L09N_5/VREF_5	AB8			
5	IO_L09P_5	AA8			
5	IO_L07N_5/VREF_5	Y8			
5	IO_L07P_5	W8			
5	IO_L06N_5/VRP_5	AD7			
5	IO_L06P_5/VRN_5	AC7			
5	IO_L05_5/No_Pair	AB7			
5	IO_L03N_5/D4	AA7			
5	IO_L03P_5/D5	Y7			
5	IO_L02N_5/D6	AC6			
5	IO_L02P_5/D7	AB6			
5	IO_L01N_5/RDWR_B	AC5			
5	IO_L01P_5/CS_B	AB5			
6	IO_L01P_6/VRN_6	AE1			
6	IO_L01N_6/VRP_6	AD1			
6	IO_L02P_6	AD2			
6	IO_L02N_6	AC3			
6	IO_L03P_6	AC2			
6	IO_L03N_6/VREF_6	AC1			
6	IO_L05P_6	AB4			
6	IO_L05N_6	AA5			
6	IO_L06P_6	AB2			
6	IO_L06N_6	AB1			
6	IO_L23P_6	AA6	NC		

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
6	IO_L52N_6	U22	NC		
6	IO_L53P_6	U23	NC		
6	IO_L53N_6	U24	NC		
6	IO_L54P_6	V26	NC		
6	IO_L54N_6	U26	NC		
6	IO_L55P_6	U20	NC		
6	IO_L55N_6	T19	NC		
6	IO_L56P_6	T20	NC		
6	IO_L56N_6	R20	NC		
6	IO_L57P_6	T21	NC		
6	IO_L57N_6/VREF_6	T22	NC		
6	IO_L58P_6	T23	NC		
6	IO_L58N_6	T24	NC		
6	IO_L59P_6	T25	NC		
6	IO_L59N_6	T26	NC		
6	IO_L60P_6	R19	NC		
6	IO_L60N_6	P19	NC		
6	IO_L85P_6	R21			
6	IO_L85N_6	R22			
6	IO_L86P_6	R23			
6	IO_L86N_6	R24			
6	IO_L87P_6	R25			
6	IO_L87N_6/VREF_6	R26			
6	IO_L88P_6	P20			
6	IO_L88N_6	P21			
6	IO_L89P_6	P22			
6	IO_L89N_6	P23			
6	IO_L90P_6	P24			
6	IO_L90N_6	P25			
7	IO_L90P_7	N25			
7	IO_L90N_7	N24			
7	IO_L89P_7	N23			
7	IO_L89N_7	N22			
7	IO_L88P_7	N21			
7	IO_L88N_7/VREF_7	N20			
7	IO_L87P_7	M26			

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R17			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U10			
N/A	GND	U12			
N/A	GND	U13			
N/A	GND	U14			
N/A	GND	U15			
N/A	GND	U17			
N/A	GND	Y20			
N/A	GND	AA21			
N/A	GND	AB22			
N/A	GND	AC23			
N/A	GND	AD24			

Notes:

1. See [Table 4](#) for an explanation of the signals available on this pin.

FF1152 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)

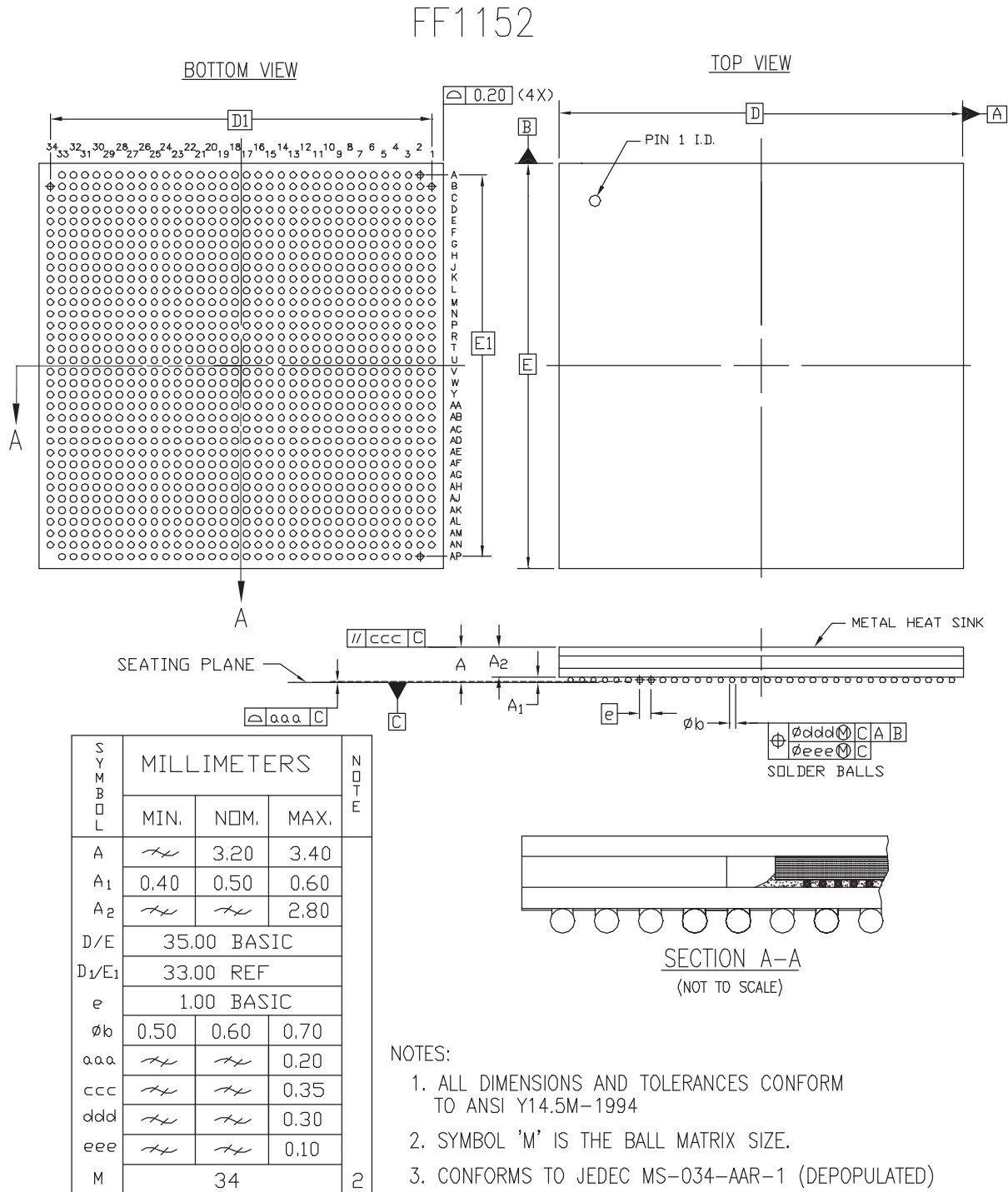


Figure 6: FF1152 Flip-Chip Fine-Pitch BGA Package Specifications

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
0	IO_L43N_0	B22		
0	IO_L43P_0	C22		
0	IO_L44N_0	K21		
0	IO_L44P_0	L21		
0	IO_L45N_0	G21		
0	IO_L45P_0/VREF_0	H21		
0	IO_L46N_0	E21		
0	IO_L46P_0	F21		
0	IO_L47N_0	K20		
0	IO_L47P_0	L20		
0	IO_L48N_0	C21		
0	IO_L48P_0	D21		
0	IO_L49N_0	A21		
0	IO_L49P_0	B21		
0	IO_L50_0/No_Pair	G20		
0	IO_L53_0/No_Pair	H19		
0	IO_L54N_0	E20		
0	IO_L54P_0	F20		
0	IO_L55N_0	C20		
0	IO_L55P_0	D19		
0	IO_L56N_0	K19		
0	IO_L56P_0	L19		
0	IO_L57N_0	A20		
0	IO_L57P_0/VREF_0	B20		
0	IO_L66N_0	F19	NC	
0	IO_L66P_0/VREF_0	G19	NC	
0	IO_L67N_0	B19		
0	IO_L67P_0	C19		
0	IO_L68N_0	H18		
0	IO_L68P_0	J18		
0	IO_L69N_0	F18		
0	IO_L69P_0/VREF_0	G18		
0	IO_L73N_0	D18		
0	IO_L73P_0	E18		
0	IO_L74N_0/GCLK7P	K18		
0	IO_L74P_0/GCLK6S	L18		
0	IO_L75N_0/GCLK5P	B18		
0	IO_L75P_0/GCLK4S	C18		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L34P_0	E27	NC	
0	IO_L35N_0	L26	NC	
0	IO_L35P_0	L25	NC	
0	IO_L36N_0	G26	NC	
0	IO_L36P_0/VREF_0	H26	NC	
0	IO_L37N_0	E26		
0	IO_L37P_0	F26		
0	IO_L38N_0	K25		
0	IO_L38P_0	K24		
0	IO_L39N_0	C26		
0	IO_L39P_0	D26		
0	IO_L43N_0	H25		
0	IO_L43P_0	J25		
0	IO_L44N_0	M25		
0	IO_L44P_0	M24		
0	IO_L45N_0	F25		
0	IO_L45P_0/VREF_0	G25		
0	IO_L46N_0	C25		
0	IO_L46P_0	D25		
0	IO_L47N_0	L23		
0	IO_L47P_0	M22		
0	IO_L48N_0	H24		
0	IO_L48P_0	J24		
0	IO_L49N_0	E25		
0	IO_L49P_0	E24		
0	IO_L50_0/No_Pair	N23		
0	IO_L53_0/No_Pair	M23		
0	IO_L54N_0	H23		
0	IO_L54P_0	J23		
0	IO_L55N_0	F24		
0	IO_L55P_0	G23		
0	IO_L56N_0	K22		
0	IO_L56P_0	L22		
0	IO_L57N_0	C23		
0	IO_L57P_0/VREF_0	D23		
0	IO_L58N_0	H22		
0	IO_L58P_0	J22		
0	IO_L59N_0	N22		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GNDA18	AU16		
N/A	TXPPAD18	AW18		
N/A	TXNPAD18	AW19		
N/A	VTTXPAD18	AV19		
N/A	AVCCAUXTX18	AV18		
N/A	AVCCAUXRX19	AV21		
N/A	VTRXPAD19	AV22		
N/A	RXNPAD19	AW21		
N/A	RXPPAD19	AW22		
N/A	GNDA19	AU24		
N/A	TXPPAD19	AW23		
N/A	TXNPAD19	AW24		
N/A	VTTXPAD19	AV24		
N/A	AVCCAUXTX19	AV23		
N/A	AVCCAUXRX20	AV25		
N/A	VTRXPAD20	AV26		
N/A	RXNPAD20	AW25		
N/A	RXPPAD20	AW26		
N/A	GNDA20	AU27		
N/A	TXPPAD20	AW27		
N/A	TXNPAD20	AW28		
N/A	VTTXPAD20	AV28		
N/A	AVCCAUXTX20	AV27		
N/A	AVCCAUXRX21	AV29		
N/A	VTRXPAD21	AV30		
N/A	RXNPAD21	AW29		
N/A	RXPPAD21	AW30		
N/A	GNDA21	AU31		
N/A	TXPPAD21	AW31		
N/A	TXNPAD21	AW32		
N/A	VTTXPAD21	AV32		
N/A	AVCCAUXTX21	AV31		
N/A	AVCCAUXRX23	AV33		
N/A	VTRXPAD23	AV34		
N/A	RXNPAD23	AW33		
N/A	RXPPAD23	AW34		
N/A	GNDA23	AU34		
N/A	TXPPAD23	AW35		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
1	IO_L48N_1		J17		
1	IO_L48P_1		H17		
1	IO_L47N_1		K17		
1	IO_L47P_1		L17		
1	IO_L46N_1		M17		
1	IO_L46P_1		M18		
1	IO_L45N_1/VREF_1		F16		
1	IO_L45P_1		E16		
1	IO_L44N_1		G16		
1	IO_L44P_1		H16		
1	IO_L43N_1		K16		
1	IO_L43P_1		J16		
1	IO_L39N_1		M16		
1	IO_L39P_1		L16		
1	IO_L38N_1		C15		
1	IO_L38P_1		C14		
1	IO_L37N_1		F15		
1	IO_L37P_1		E15		
1	IO_L87N_1/VREF_1		J15	NC	
1	IO_L87P_1		H15	NC	
1	IO_L86N_1		K15	NC	
1	IO_L86P_1		L15	NC	
1	IO_L85N_1		E14	NC	
1	IO_L85P_1		D14	NC	
1	IO_L84N_1		G14	NC	
1	IO_L84P_1		F14	NC	
1	IO_L83_1/No_Pair		H14	NC	
1	IO_L78N_1		L14	NC	
1	IO_L78P_1		K14	NC	
1	IO_L36N_1/VREF_1		M14		
1	IO_L36P_1		M15		
1	IO_L35N_1		C13		
1	IO_L35P_1		D13		
1	IO_L34N_1		F13		
1	IO_L34P_1		E13		
1	IO_L30N_1		H13		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
1	IO_L30P_1		G13		
1	IO_L29N_1		K13		
1	IO_L29P_1		J13		
1	IO_L28N_1		M13		
1	IO_L28P_1		L13		
1	IO_L27N_1/VREF_1		E12		
1	IO_L27P_1		D12		
1	IO_L26N_1		F12		
1	IO_L26P_1		G12		
1	IO_L25N_1		J12		
1	IO_L25P_1		H12		
1	IO_L21N_1		L12		
1	IO_L21P_1		K12		
1	IO_L20N_1		C11		
1	IO_L20P_1		C10		
1	IO_L19N_1		F11		
1	IO_L19P_1		E11		
1	IO_L09N_1/VREF_1		J11		
1	IO_L09P_1		H11		
1	IO_L08N_1		D10		
1	IO_L08P_1		E10		
1	IO_L07N_1		G10		
1	IO_L07P_1		F10		
1	IO_L06N_1		J10		
1	IO_L06P_1		H10		
1	IO_L05_1/No_Pair		K11		
1	IO_L03N_1/VREF_1		D9		
1	IO_L03P_1		C9		
1	IO_L02N_1		E9		
1	IO_L02P_1		F9		
1	IO_L01N_1/VRP_1		H9		
1	IO_L01P_1/VRN_1		G9		
2	IO_L01N_2/VRP_2		C5		
2	IO_L01P_2/VRN_2		C6		
2	IO_L02N_2		E7		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
6	IO_L52N_6		AE42		
6	IO_L53P_6		AE32		
6	IO_L53N_6		AE33		
6	IO_L54P_6		AD35		
6	IO_L54N_6		AD36		
6	IO_L55P_6		AD37		
6	IO_L55N_6		AD38		
6	IO_L56P_6		AD31		
6	IO_L56N_6		AD32		
6	IO_L57P_6		AD39		
6	IO_L57N_6/VREF_6		AD40		
6	IO_L58P_6		AD41		
6	IO_L58N_6		AD42		
6	IO_L59P_6		AD33		
6	IO_L59N_6		AD34		
6	IO_L60P_6		AC33		
6	IO_L60N_6		AC34		
6	IO_L85P_6		AC36		
6	IO_L85N_6		AC37		
6	IO_L86P_6		AC31		
6	IO_L86N_6		AC32		
6	IO_L87P_6		AC39		
6	IO_L87N_6/VREF_6		AC40		
6	IO_L88P_6		AB33		
6	IO_L88N_6		AB34		
6	IO_L89P_6		AB36		
6	IO_L89N_6		AB37		
6	IO_L90P_6		AB39		
6	IO_L90N_6		AB40		
7	IO_L90P_7		AA39		
7	IO_L90N_7		AA40		
7	IO_L89P_7		AB31		
7	IO_L89N_7		AA31		
7	IO_L88P_7		AA36		
7	IO_L88N_7/VREF_7		AA37		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	GND		AB18		
N/A	GND		AB17		
N/A	GND		AB11		
N/A	GND		AB8		
N/A	GND		AB5		
N/A	GND		AC41		
N/A	GND		AC26		
N/A	GND		AC25		
N/A	GND		AC24		
N/A	GND		AC23		
N/A	GND		AC22		
N/A	GND		AC21		
N/A	GND		AC20		
N/A	GND		AC19		
N/A	GND		AC18		
N/A	GND		AC17		
N/A	GND		AC2		
N/A	GND		AD26		
N/A	GND		AD25		
N/A	GND		AD24		
N/A	GND		AD23		
N/A	GND		AD22		
N/A	GND		AD21		
N/A	GND		AD20		
N/A	GND		AD19		
N/A	GND		AD18		
N/A	GND		AD17		
N/A	GND		AE37		
N/A	GND		AE34		
N/A	GND		AE26		
N/A	GND		AE25		
N/A	GND		AE24		
N/A	GND		AE23		
N/A	GND		AE22		
N/A	GND		AE21		
N/A	GND		AE20		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	IO_L22N_2/VREF_2	L4	
2	IO_L22P_2	L5	
2	IO_L23N_2	T8	
2	IO_L23P_2	T9	
2	IO_L24N_2	L3	
2	IO_L24P_2	K3	
2	IO_L25N_2	L1	
2	IO_L25P_2	L2	
2	IO_L26N_2	U12	
2	IO_L26P_2	V12	
2	IO_L27N_2	M7	
2	IO_L27P_2	L6	
2	IO_L28N_2/VREF_2	M5	
2	IO_L28P_2	M6	
2	IO_L29N_2	U10	
2	IO_L29P_2	U11	
2	IO_L30N_2	M3	
2	IO_L30P_2	M4	
2	IO_L31N_2	N6	
2	IO_L31P_2	N7	
2	IO_L32N_2	U7	
2	IO_L32P_2	U8	
2	IO_L33N_2	N3	
2	IO_L33P_2	N4	
2	IO_L34N_2/VREF_2	N2	
2	IO_L34P_2	M2	
2	IO_L35N_2	V10	
2	IO_L35P_2	V11	
2	IO_L36N_2	P6	
2	IO_L36P_2	P7	
2	IO_L37N_2	P1	
2	IO_L37P_2	P2	
2	IO_L38N_2	V8	
2	IO_L38P_2	V9	
2	IO_L39N_2	R6	
2	IO_L39P_2	P5	
2	IO_L40N_2/VREF_2	R4	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	VCCO_2	F4	
1	VCCO_1	R21	
1	VCCO_1	P21	
1	VCCO_1	R20	
1	VCCO_1	P20	
1	VCCO_1	R19	
1	VCCO_1	P19	
1	VCCO_1	R18	
1	VCCO_1	P18	
1	VCCO_1	H18	
1	VCCO_1	D18	
1	VCCO_1	P17	
1	VCCO_1	H14	
1	VCCO_1	D14	
1	VCCO_1	M13	
1	VCCO_1	D10	
0	VCCO_0	D33	
0	VCCO_0	M30	
0	VCCO_0	H29	
0	VCCO_0	D29	
0	VCCO_0	P26	
0	VCCO_0	R25	
0	VCCO_0	P25	
0	VCCO_0	H25	
0	VCCO_0	D25	
0	VCCO_0	R24	
0	VCCO_0	P24	
0	VCCO_0	R23	
0	VCCO_0	P23	
0	VCCO_0	R22	
0	VCCO_0	P22	
N/A	CCLK	AM10	
N/A	PROG_B	J33	
N/A	DONE	AN10	
N/A	M0	AP33	
N/A	M1	AN33	

FF1696 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)

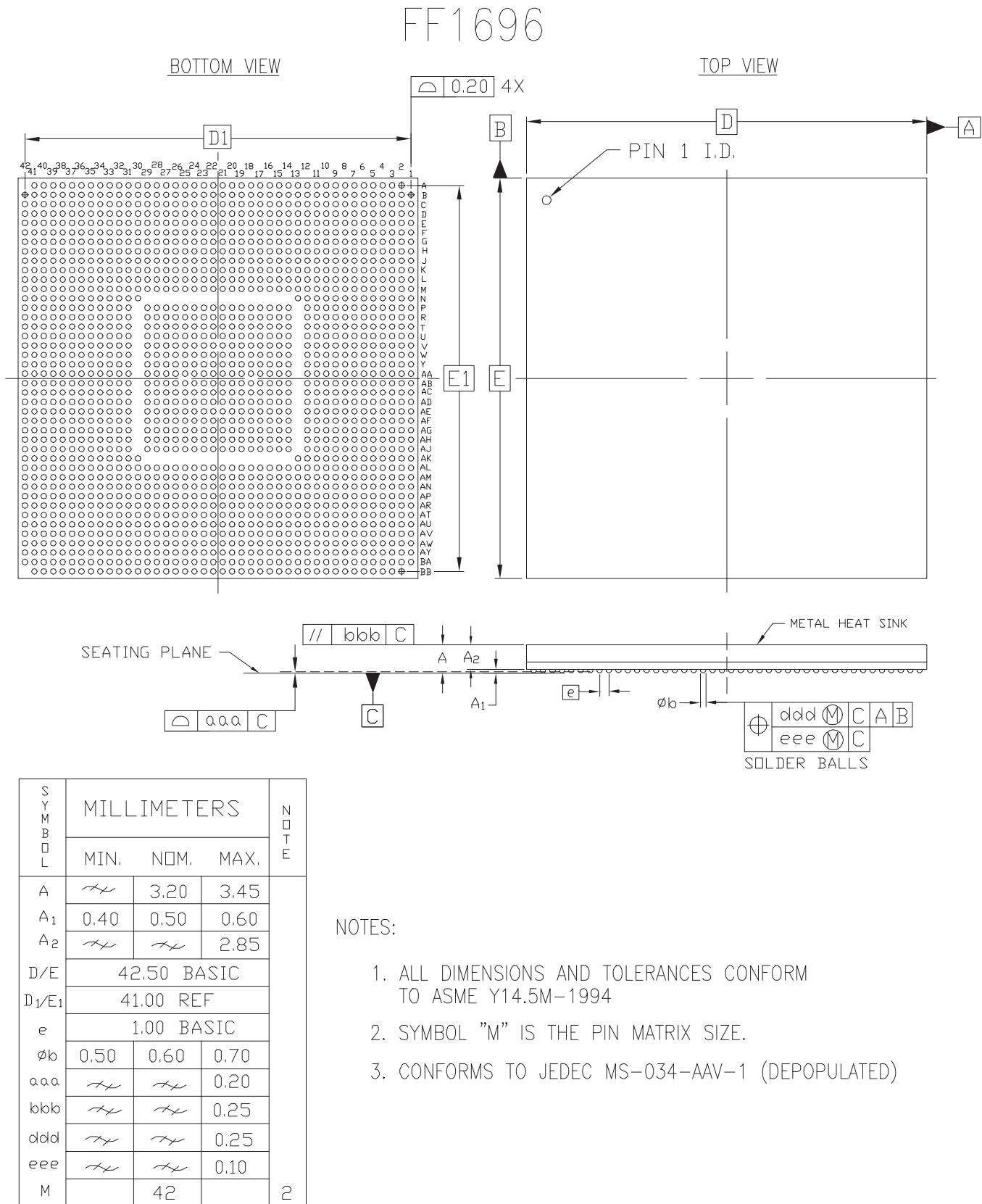


Figure 10: FF1696 Flip-Chip Fine-Pitch BGA Package Specifications

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
08/14/02	2.0	Added package and pinout information for new devices.
08/27/02	2.1	- Updated SelectIO-Ultra information in Table 4. (Table deleted in v2.3.) - Corrected direction for RXNPAD and TXPPAD in Table 4 (formerly Table 5).
09/27/02	2.2	Corrected Table 2 and Table 3 entries for XC2VP30, FF1152 package, maximum I/Os from 692 to 644.
11/20/02	2.3	Added Number of Differential Pairs data to Table 3 . Removed former Table 4.
12/03/02	2.4	Corrections in Table 4 : - Reclassified GCLKx (S/P) pins as Input/Output, since these pins can be used as normal I/Os if not used as clocks. - Added cautionary note to PWRDWN_B pin, indicating that this function is not supported.
01/20/03	2.5	Added and removed package/pinout information for existing devices: - In Table 1, added FG676 package information. - In Table 3, added FG676 package option for XC2VP20, XC2VP30, and XC2VP40. - In Table 12, removed FF1517 package option for XC2VP40. - Added FG676 package pinouts (Table 7) for XC2VP20, XC2VP30, and XC2VP40. - Added package diagram (Figure 3) for FG676 package.
05/19/03	2.5.1	- Added section BREFCLK Pin Definitions, page 5. - Added clarification to Table 4 and all device pinout tables regarding the dual-use nature of pins D0/DIN and BUSY/DOUT during configuration.
06/19/03	2.5.3	- Added notation of "open-drain" to TDO pin in Table 4. - The final GND pin in each of six pinout tables was inadvertently deleted in v2.5.1. This revision restores the deleted GND pins as follows: - Pin A1, Table 6, page 16 (FG456) - Pin AF26, Table 7, page 30 (FG676) - Pin AN34, Table 10, page 98 (FF1152) - Pin E1, Table 11, page 130 (FF1148) - Pin C38, Table 12, page 162 (FF1517) - Pin E1, Table 14, page 253 (FF1696)
08/25/03	2.5.5	Table 4: Deleted Note 2, obsolete. There is only one GNDA pin per MGT. Table 4: Deleted pins ALT_VRP and ALT_VRN. Not used in Virtex-II Pro FPGAs.
12/10/03	3.0	XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, are released to Production status .
02/19/04	3.1	Table 4, signal descriptions column: - For signals TDI, TMS, and TCK, added: Pins are 3.3V-compatible. - For signals M2, M1, M0, added: Tie to 3.3V only with 100Ω series resistor. No toggling during or after configuration. - For signal TDO, added: No internal pull-up. External pull-up to 3.3V OK with resistor greater than 200Ω.
03/09/04	3.1.1	Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
06/30/04	4.0	Merged in DS110-4 (Module 4 of Virtex-II Pro X data sheet). Added data on available Pb-free packages and updated package diagrams for affected devices.